L Number	Hits	Search Text	DB	Time stamp
1	1625192	etch$ or patern$ or remov$	JPO; DERWENT	2004/10/15 10:36
2	2012874	(bond$ pad) or (contact pad)	JPO; DERWENT	2004/10/15 10:37
3	307877	resist or photoresist or mask or photomask	JPO; DERWENT	2004/10/15 10:38
4	17602	passivat$	JPO; DERWENT	2004/10/15 10:38
5	641458	adhes$	JPO; DERWENT	2004/10/15 10:38
6	2225243	adhes$ layer	JPO; DERWENT	2004/10/15 10:38
7	17348	(etch$ or patern$ or remov$) and ((bond$ pad) or (contact pad)) and (resist or photoresist or mask or photomask) and (passivat$ or (adhes$ layer))	JPO; DERWENT	2004/10/15 10:39
8	36628	(bond$ with pad) or (contact with pad)	JPO; DERWENT	2004/10/15 10:39
9	149036	adhes$ with layer	JPO; DERWENT	2004/10/15 10:40
10	8016	(etch$ or patern$ or remov$) with (adhes$ with layer)	JPO; DERWENT	2004/10/15 10:40
11	7928	passivat$ with layer	JPO; DERWENT	2004/10/15 10:40
12	1765	(etch$ or patern$ or remov$) with (passivat$ with layer)	JPO; DERWENT	2004/10/15 10:40
13	635	(((etch$ or patern$ or remov$) with (adhes$ with layer)) or ((etch$ or patern$ or remov$) with (passivat$ with layer))) and (resist or photoresist or mask or photomask) and ((bond$ pad) or (contact pad))	JPO; DERWENT	2004/10/15 10:41
14	635	(etch$ or patern$ or remov$) and ((((etch$ or patern$ or remov$) with (adhes$ with layer)) or ((etch$ or patern$ or remov$) with (passivat$ with layer))) and (resist or photoresist or mask or photomask) and ((bond$ pad) or (contact pad)))	JPO; DERWENT	2004/10/15 10:41
15	20586	bond$ with pad	JPO; DERWENT	2004/10/15 10:41
16	73	((etch$ or patern$ or remov$) and ((((etch$ or patern$ or remov$) with (adhes$ with layer)) or ((etch$ or patern$ or remov$) with (passivat$ with layer))) and (resist or photoresist or mask or photomask) and ((bond$ pad) or (contact pad)))) and (bond$ with pad)	JPO; DERWENT	2004/10/15 11:15
17	562	((etch$ or patern$ or remov$) and ((((etch$ or patern$ or remov$) with (adhes$ with layer)) or ((etch$ or patern$ or remov$) with (passivat$ with layer))) and (resist or photoresist or mask or photomask) and ((bond$ pad) or (contact pad)))) not (bond$ with pad)	JPO; DERWENT	2004/10/15 11:15
18	57	(((etch$ or patern$ or remov$) and ((((etch$ or patern$ or remov$) with (adhes$ with layer)) or ((etch$ or patern$ or remov$) with (passivat$ with layer))) and (resist or photoresist or mask or photomask) and ((bond$ pad) or (contact pad)))) not (bond$ with pad)) and solder$	JPO; DERWENT	2004/10/15 11:15

C:\APPS\east\workspaces\bond.wsp

L Number	Hits	Search Text	DB	Time stamp
1	1625192	etch$ or patern$ or remov$	JPO; DERWENT	2004/10/15 10:36
2	2012874	(bond$ pad) or (contact pad)	JPO; DERWENT	2004/10/15 10:37
3	307877	resist or photoresist or mask or photomask	JPO; DERWENT	2004/10/15 10:38
4	17602	passivat$	JPO; DERWENT	2004/10/15 10:38
5	641458	adhes$	JPO; DERWENT	2004/10/15 10:38
6	2225243	adhes$ layer	JPO; DERWENT	2004/10/15 10:38
7	17348	(etch$ or patern$ or remov$) and ((bond$ pad) or (contact pad)) and (resist or photoresist or mask or photomask) and (passivat$ or (adhes$ layer))	JPO; DERWENT	2004/10/15 10:39
8	36628	(bond$ with pad) or (contact with pad)	JPO; DERWENT	2004/10/15 10:39
9	149036	adhes$ with layer	JPO; DERWENT	2004/10/15 10:40
10	8016	(etch$ or patern$ or remov$) with (adhes$ with layer)	JPO; DERWENT	2004/10/15 10:40
11	7928	passivat$ with layer	JPO; DERWENT	2004/10/15 10:40
12	1765	(etch$ or patern$ or remov$) with (passivat$ with layer)	JPO; DERWENT	2004/10/15 10:40
13	635	(((etch$ or patern$ or remov$) with (adhes$ with layer)) or ((etch$ or patern$ or remov$) with (passivat$ with layer))) and (resist or photoresist or mask or photomask) and ((bond$ pad) or (contact pad))	JPO; DERWENT	2004/10/15 10:41
14	635	(etch$ or patern$ or remov$) and ((((etch$ or patern$ or remov$) with (adhes$ with layer)) or ((etch$ or patern$ or remov$) with (passivat$ with layer))) and (resist or photoresist or mask or photomask) and ((bond$ pad) or (contact pad)))	JPO; DERWENT	2004/10/15 10:41
15	20586	bond$ with pad	JPO; DERWENT	2004/10/15 10:41
16	73	((etch$ or patern$ or remov$) and ((((etch$ or patern$ or remov$) with (adhes$ with layer)) or ((etch$ or patern$ or remov$) with (passivat$ with layer))) and (resist or photoresist or mask or photomask) and ((bond$ pad) or (contact pad)))) and (bond$ with pad)	JPO; DERWENT	2004/10/15 11:15
17	562	((etch$ or patern$ or remov$) and ((((etch$ or patern$ or remov$) with (adhes$ with layer)) or ((etch$ or patern$ or remov$) with (passivat$ with layer))) and (resist or photoresist or mask or photomask) and ((bond$ pad) or (contact pad)))) not (bond$ with pad)	JPO; DERWENT	2004/10/15 11:15
18	57	(((etch$ or patern$ or remov$) and ((((etch$ or patern$ or remov$) with (adhes$ with layer)) or ((etch$ or patern$ or remov$) with (passivat$ with layer))) and (resist or photoresist or mask or photomask) and ((bond$ pad) or (contact pad)))) not (bond$ with pad)) and solder$	JPO; DERWENT	2004/10/15 11:25
19	505	(((etch$ or patern$ or remov$) and ((((etch$ or patern$ or remov$) with (adhes$ with layer)) or ((etch$ or patern$ or remov$) with (passivat$ with layer))) and (resist or photoresist or mask or photomask) and ((bond$ pad) or (contact pad)))) not (bond$ with pad)) not (((((etch$ or patern$ or remov$) and ((((etch$ or patern$ or remov$) with (adhes$ with layer)) or ((etch$ or patern$ or remov$) with (passivat$ with layer))) and (resist or photoresist or mask or photomask) and ((bond$ pad) or (contact pad)))) not (bond$ with pad)) and solder$)	JPO; DERWENT	2004/10/15 11:26

20	33	(((((etch$ or patern$ or remov$) and (((((etch$ or patern$ or remov$) with (adhes$ with layer)) or ((etch$ or patern$ or remov$) with (passivat$ with layer))) and (resist or photoresist or mask or photomask) and ((bond$ pad) or (contact pad)))) not (bond$ with pad)) not (((((etch$ or patern$ or remov$) and (((((etch$ or patern$ or remov$) with (adhes$ with layer)) or ((etch$ or patern$ or remov$) with (passivat$ with layer))) and (resist or photoresist or mask or photomask) and ((bond$ pad) or (contact pad)))) not (bond$ with pad)) and solder$)) and ("438" or "216")	JPO; DERWENT	2004/10/15 11:33
21	472	(((((etch$ or patern$ or remov$) and (((((etch$ or patern$ or remov$) with (adhes$ with layer)) or ((etch$ or patern$ or remov$) with (passivat$ with layer))) and (resist or photoresist or mask or photomask) and ((bond$ pad) or (contact pad)))) not (bond$ with pad)) not (((((etch$ or patern$ or remov$) and (((((etch$ or patern$ or remov$) with (adhes$ with layer)) or ((etch$ or patern$ or remov$) with (passivat$ with layer))) and (resist or photoresist or mask or photomask) and ((bond$ pad) or (contact pad)))) not (bond$ with pad)) and solder$)) not (((((etch$ or patern$ or remov$) and (((((etch$ or patern$ or remov$) with (adhes$ with layer)) or ((etch$ or patern$ or remov$) with (passivat$ with layer))) and (resist or photoresist or mask or photomask) and ((bond$ pad) or (contact pad)))) not (bond$ with pad)) not (((((etch$ or patern$ or remov$) and (((((etch$ or patern$ or remov$) with (adhes$ with layer)) or ((etch$ or patern$ or remov$) with (passivat$ with layer))) and (resist or photoresist or mask or photomask) and ((bond$ pad) or (contact pad)))) not (bond$ with pad)) and solder$)) and ("438" or "216"))	JPO; DERWENT	2004/10/15 11:33
22	8	((((((etch$ or patern$ or remov$) and (((((etch$ or patern$ or remov$) with (adhes$ with layer)) or ((etch$ or patern$ or remov$) with (passivat$ with layer))) and (resist or photoresist or mask or photomask) and ((bond$ pad) or (contact pad)))) not (bond$ with pad)) not (((((etch$ or patern$ or remov$) and (((((etch$ or patern$ or remov$) with (adhes$ with layer)) or ((etch$ or patern$ or remov$) with (passivat$ with layer))) and (resist or photoresist or mask or photomask) and ((bond$ pad) or (contact pad)))) not (bond$ with pad)) and solder$)) not (((((etch$ or patern$ or remov$) and (((((etch$ or patern$ or remov$) with (adhes$ with layer)) or ((etch$ or patern$ or remov$) with (passivat$ with layer))) and (resist or photoresist or mask or photomask) and ((bond$ pad) or (contact pad)))) not (bond$ with pad)) not (((((etch$ or patern$ or remov$) and (((((etch$ or patern$ or remov$) with (adhes$ with layer)) or ((etch$ or patern$ or remov$) with (passivat$ with layer))) and (resist or photoresist or mask or photomask) and ((bond$ pad) or (contact pad)))) not (bond$ with pad)) and solder$)) and ("438" or "216"))) and ("156" or "437" or "257")	JPO; DERWENT	2004/10/15 11:35

C:\APPS\east\workspaces\bond.wsp

| 23 | 464 | (((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) not (((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) and solder\$)) not ((((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) not (((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) and solder\$)) and ("438" or "216"))) not ((((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) not (((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) not (((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) and solder\$)) and ("438" or "216"))) and ("156" or "437" or "257")) | JPO; DERWENT | 2004/10/15 11:35 |